

2023/10

ADEKA REMYLOP CLS-1194

Product Features

- One-component heat curing adhesive
- High thermal resistance
- Epoxy type (Halogen-free available)

Properties (uncured)

Viscosity / 25°C	0.5 rpm	10	Pa · s
	5 rpm	4	Pa · s
Thixotropic value	0.5 rpm/5 rpm	2.5	
Specific gravity		1.17	
Filler content		0	wt %
Nonvolatile content		> 99	%
Pot Life	25 °C	168	hrs
Shelf Life	≤ 5 °C	4	months
Viscosity / 25°C	≤ -18 °C	12	months

Cured Material Properties

Glass transition temperature	TMA	177	°C
	DMA	250	°C
Hardness	ShoreD	> D80	
Storage modulus/ 25°C	DMA at 25 °C	2.5	GPa
	DMA at 180 °C	1.3	GPa
Coefficient of linear expansion	α 1	45	ppm

DSC : SII DCS6220 25 – 300 °C (10 °C/min)

DMA : TA RSA-G2 25 – 300 °C (10 °C/min),
curing condition ; 180 °C × 1 hr

TMA : SII TMA/SS6100 25 – 300 °C (5 °C/min),
curing condition ; 180 °C × 1 hr

Curing characteristics

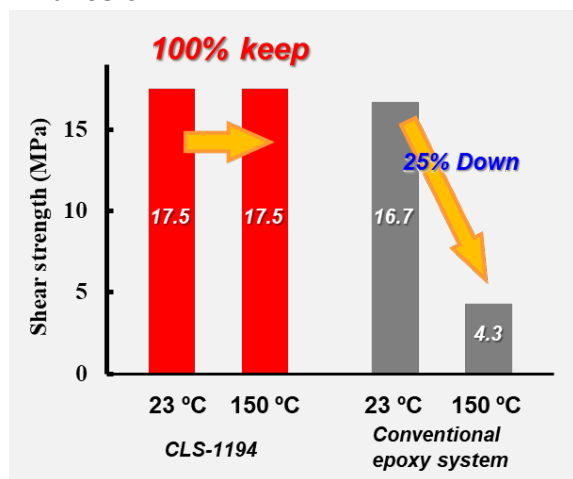
Maximum exothermic temp. of DSC	185	°C
Maximum exothermic value of DSC	750	mJ/mg

Recommended Curing Conditions

180 °C

> 30 min

Adhesion



Fe/Fe Shear adhesion test (180 °C × 1 hr)

Usage

【Storage】 Store in a sealed container at temperature below 5 °C (-18 °C recommended)

【Breaking the seal】 To prevent moisture condensation, please bring the product to room temperature before opening the package.

【Curing】 The adhesive must be heated sufficiently to reach the curing temperature. Curing conditions vary depending on the thermal capacity of the adherend and surrounding parts, the method of use, and the amount of coating applied.

【Disposal】 Please refer to SDS for proper treatment.

【Others】 Please contact us at the following

株式会社 ADEKA

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Tell 03-4455-2843

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